SPECIFICATION
FOR
LCM+CTP Module

MODULE:	**KD035HVFIA141-C009A**
CUSTOMER:	

REV	DESCRIPTION	DATE
1.0	FIRST ISSUE	2020.08.20

STARTEK	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		

Revision History

Date	Rev. No.	Page	Summary
2020.08.20	V1.0	ALL	FIRST ISSUE

Contents

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorpho us silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit,back-light unit. The resolution of a 3.5'TFT-LCD contains 320x480 pixels, and can displa y up to 65K/262K/16.7M colors.

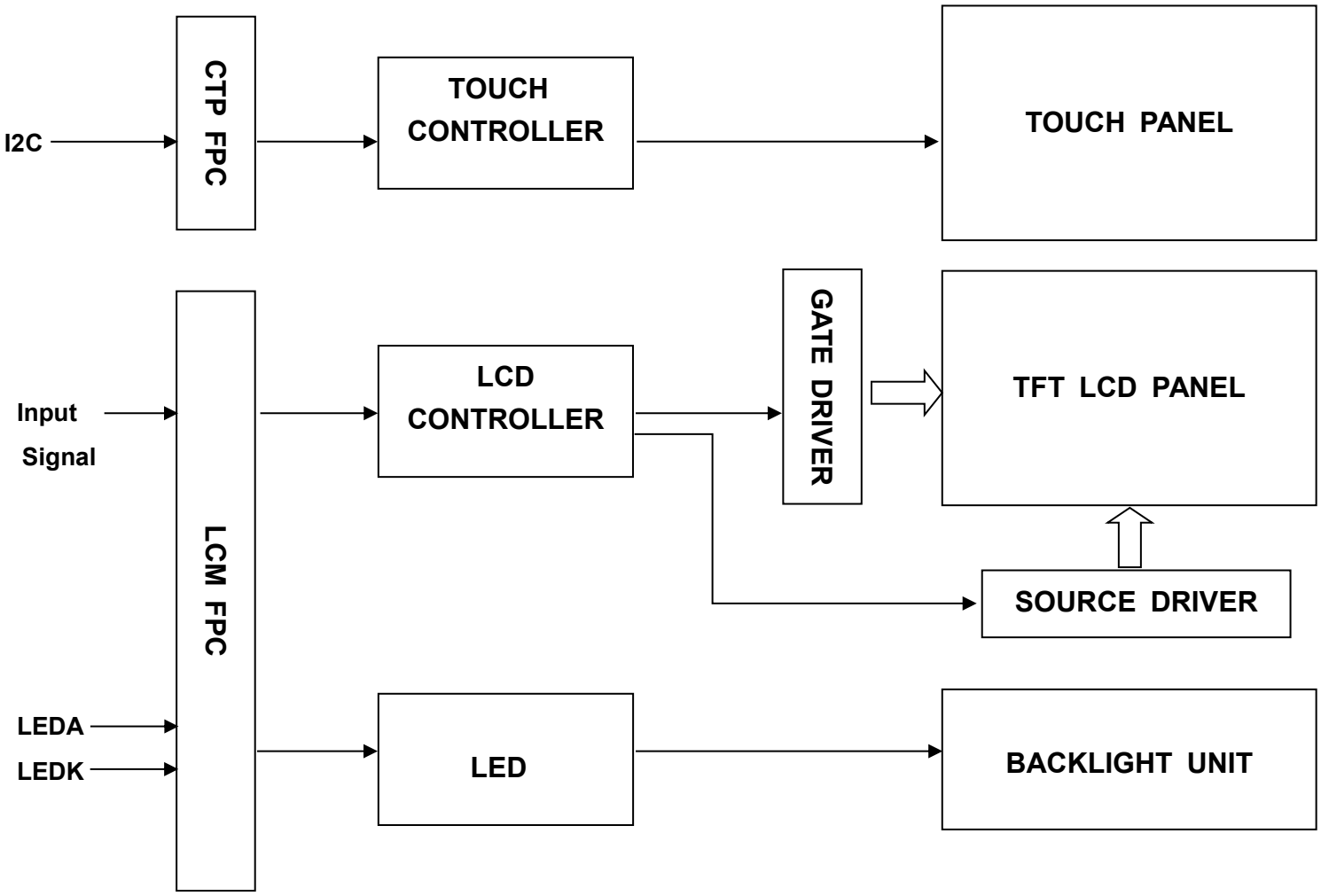
* Features

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	48.96(H)*73.44(V) (3.5inch)	mm	-
CTP View area	49.56(H)*74.04(V)	mm	
Driver element	TFT active matrix	-	-
Display colors	65K/262K/16.7M	colors	-
Number of pixels	320(RGB)*480	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.153(H) x 0.153(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ILI9488	-	-
LCM Interface	1-line MIPI Interface	--	--
CTP Driver IC	FT6336G		
CTP Interface	I2C	--	--
Display mode	Transmissive/Normally Black	-	-
Touch mode	Single point and Gestures		
Operating temperature	-20～+70	℃	-
Storage temperature	-30～+80	℃	-

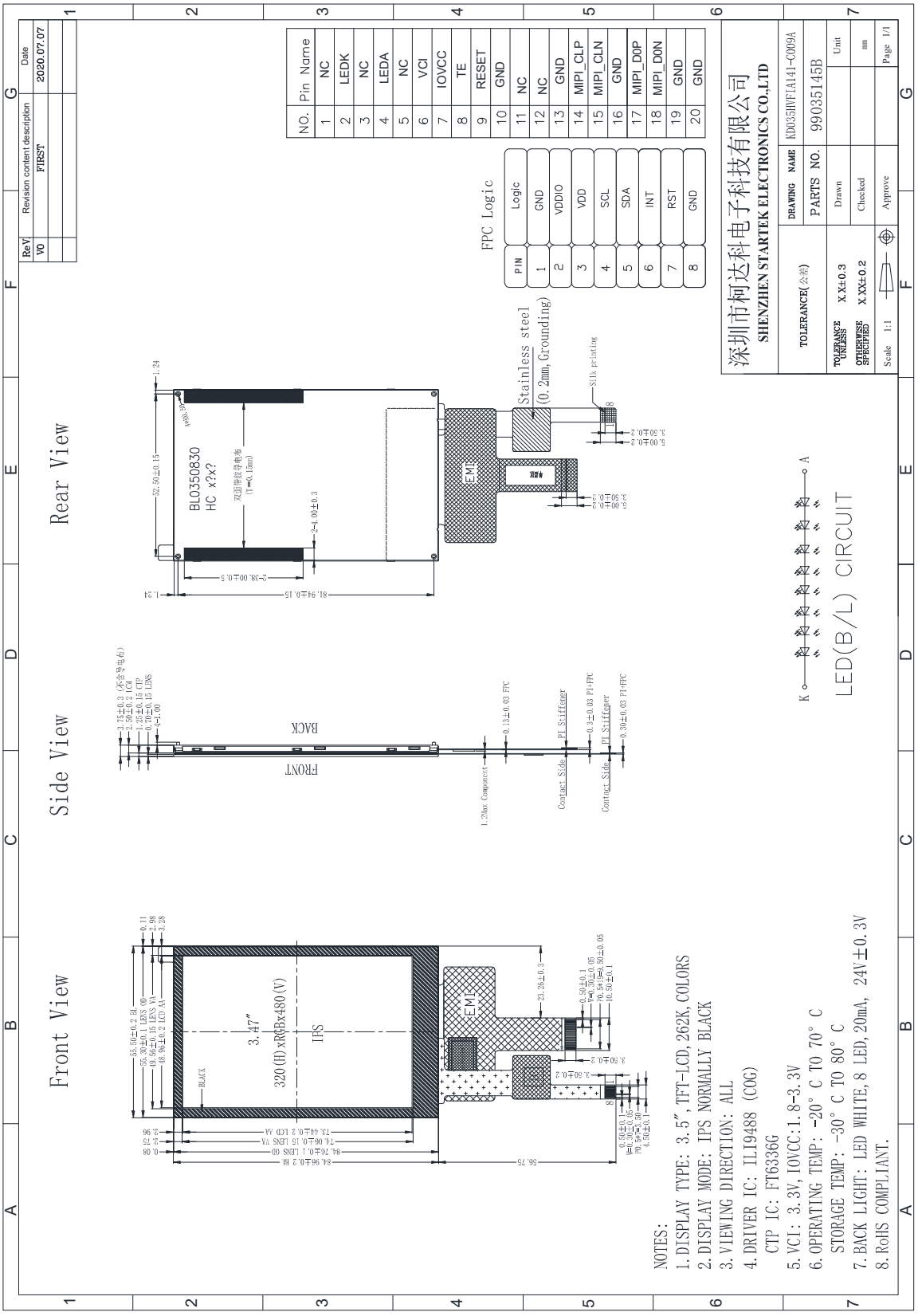
* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		55.50		mm	-
	Vertical(V)		84.96		mm	-
	Depth(D)		3.75		mm	-
Weight			35		g	-

1. Block Diagram



2. Outline dimension



3. Input terminal Pin Assignment

3.1 TFT

NO.	SYMBOL	DISCRIPTION	I/O
1	NC	NC	
2	LEDK	Cathode pin of backlight.	P
3	NC	NC	
4	LEDA	Anode pin of backlight.	P
5	NC	NC	
6	VCI	Supply Voltage (3.3V).	P
7	IOVCC	I/O power supply voltage.(1.8~3.3V)	P
8	TE	-Tearing effect output Leave the pin to open when not in use.	O
9	RESET	- The external reset input. Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power.	I
10	GND	Ground.	P
11	NC	NC	I/O
12	NC	NC	I/O
13	GND	Ground.	P
14	MIPI_CLP	MIPI DSI differential clock pair (DSI-CLK+/-)..	I
15	MIPI_CLN		I
16	GND	Ground.	P
17	MIPI_D0P	MIPI DSI differential data pair (DSI-Dn+/-).	I/O
18	MIPI_D0N		I/O
19	GND	Ground.	P
20	GND	Ground.	P

3.2 CTP

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VDDIO	I/O power supply voltage.	P
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host.	I
7	RST	External Reset, Low is active.	I
8	GND	Ground.	P

4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0 Normal viewing angle	500	600	--		(1)(2)
Response time	Rising	T_R		--	35	50	msec	(1)(3)
	Falling	T_F						
Color gamut		S(%)		--	66	--	%	C-light
Color Filter Chromacicity	White	W_X		0.3006	0.3017	0.3031		(1)(4)
		W_Y		0.3411	0.3420	0.3445		
	Red	R_X		0.6223	0.6263	0.6271		
		R_Y		0.3387	0.3460	0.3475		
	Green	G_X		0.3053	0.3064	0.3075		
		G_Y		0.5816	0.5846	0.5854		
	Blue	B_X		0.1484	0.1492	0.1493		
		B_Y		0.0487	0.0494	0.0500		
Viewing angle	Hor.	Θ_L	CR>10	--	80	--		(1)(4)
		Θ_R		--	80	--		
	Ver.	Θ_U		--	80	--		
		Θ_D		--	80	--		
Option View Direction		Free						(5)

*The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room

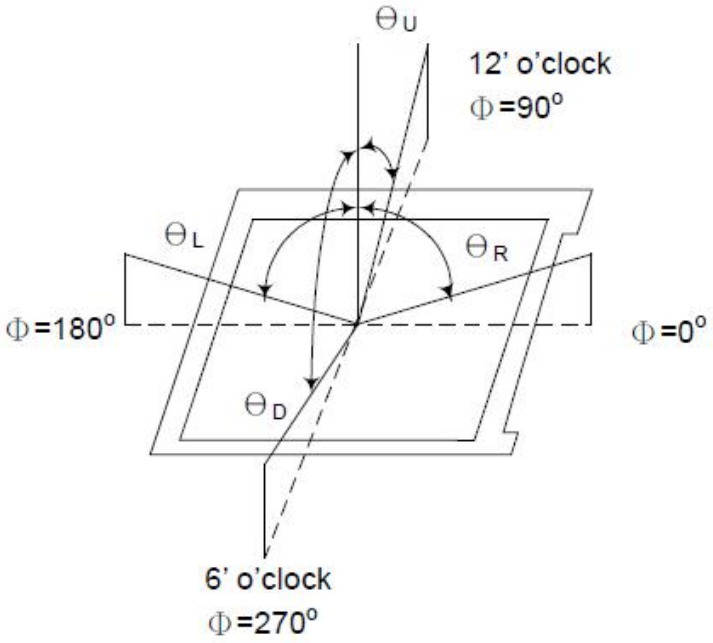
Ambient temperature : 25±2°C

15min. warm-up time.

Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

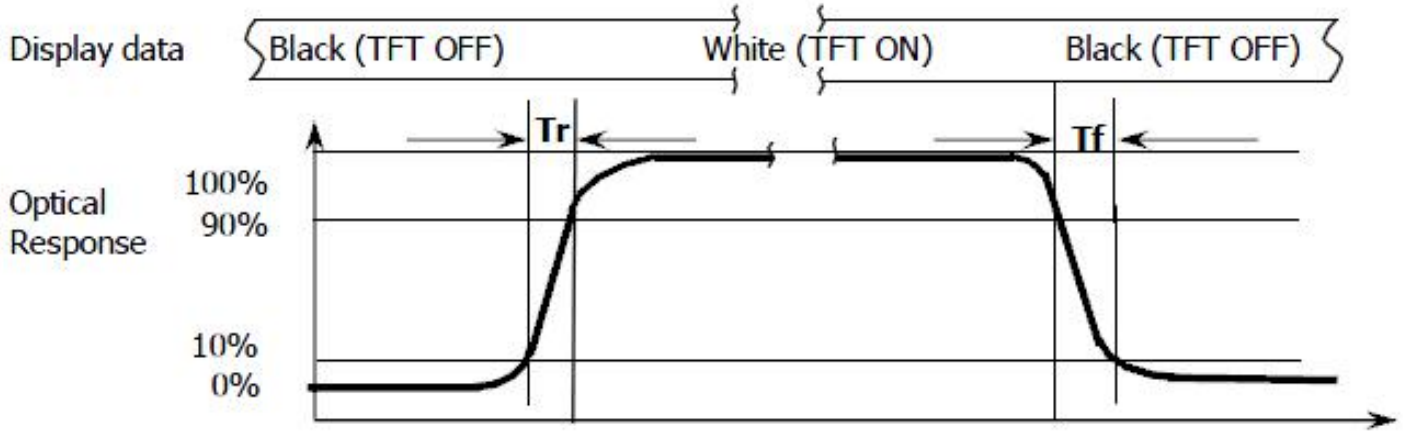
Note (1): Definition of Viewing Angle :



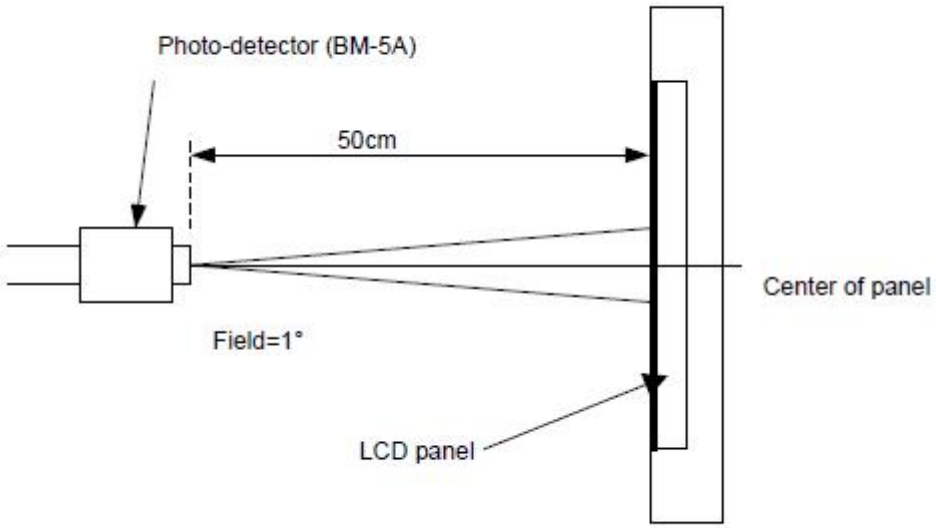
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3): Response Time



Note (4): Definition of optical measurement setup



5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCI	-0.3	4.6	**V**
Digital interface supple Voltage	IOVCC	-0.3	4.6	**V**
Operating temperature	T_{OP}	-20	+70	℃
Storage temperature	T_{ST}	-30	+80	℃

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DSI DC Characteristics

DSI is using different state codes which are depending on DC voltage levels of the clock and data lanes. The meaning of the state codes is defined on the following table.

State Code	Line DC Voltage Levels	
	CLOCK_P or DATA_P	CLOCK_N or DATA_N
HS-0	Low (HS)	High (HS)
HS-1	High (HS)	Low (HS)
LP-00	Low (LP)	Low (LP)
LP-01	Low (LP)	Low (LP)
LP-10	High (LP)	High (LP)
LP-11	High (LP)	High (LP)

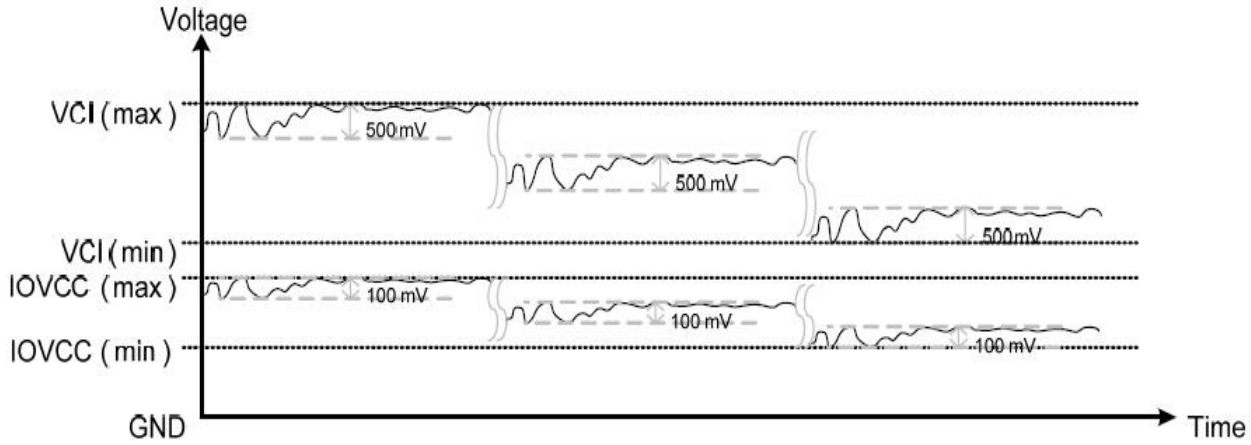
Note: Ta=-30℃ to 70℃ (to +85℃ no damage)

5.2.1 DC Characteristics for Power Lines

Characteristics	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Analog power supply voltage	VCI	Operating voltage	2.5	2.8/3.3	3.6	V	--
Digital interface supple Voltage	IOVCC	I/O supply voltage	1.65	1.8	3.6	V	--
Normal mode Current consumption	IDD	VCI+IOVCC	--	14	--	mA	
Analog power supply voltage noise	V_{VCI_NOISE}	Noise Range, 0 to 30kHz, Pulse Wave with Duty Cycle (50%/50%)	--	--	100	mV	--
	V_{IOVCC_NOISE}	Noise Range, 0 to 100MHz, Sinusoidal Wave (peak-to-peak)	--	--	500	mV	--
I/O power supply voltage noise	V_{IOVCC_NOISE}	Noise Range, 0 to 100MHz, Sinusoidal Wave (peak-to-peak)	--	--	100	mV	--

Note:

1. Ta=-30℃ to 70℃ (to +85℃ no damage)
2. These values are not symmetric amplitude, which centersm3g points are IOVCC or VCI. See examples as reference purposes, when V_{VCI_NOISE} and V_{IOVCC_NOISE} are maximums, below.



Noise on Power Supply Lines

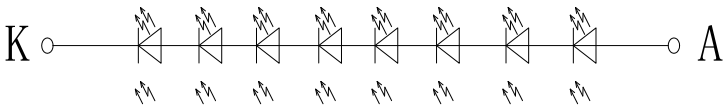
5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 8 chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	15	20	--	mA	
Forward Voltage	V_F	--	25.6	--	V	
LCM Luminance	L_V	400	450	--	cd/m2	Note3
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

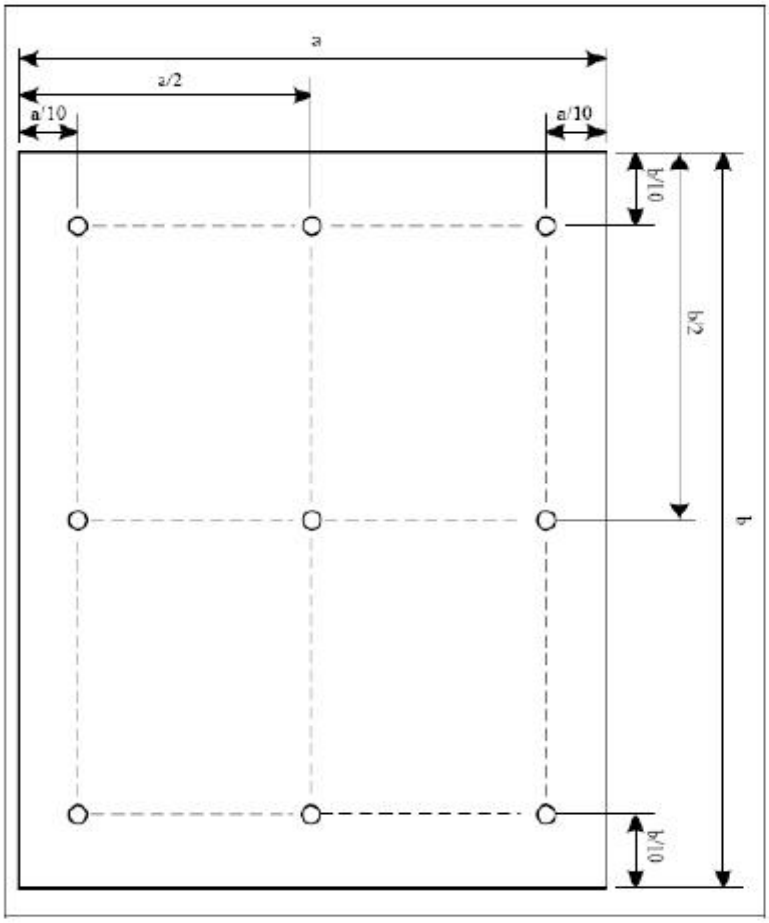
Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



LED(B/L) CIRCUIT

NOTE 3：Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

6. MIPI Interface Characteristics

6.1 High Speed Mode – Clock Channel Timing

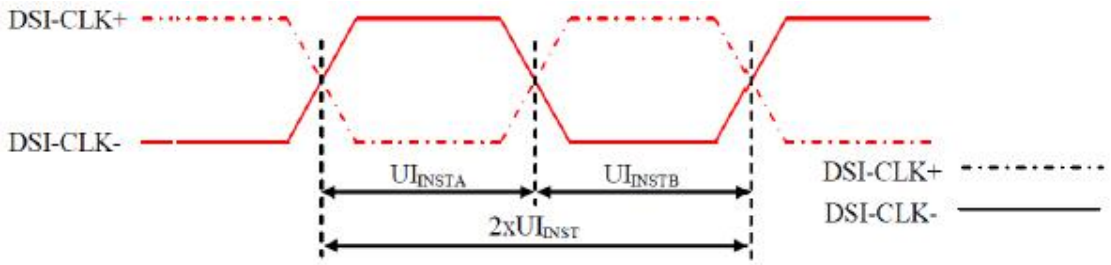


Figure 114 DSI Clock Channel Timing

Table 45 DSI Clock Channel Timing

Signal	Symbol	Parameter	Min	Max	Unit
DSI-CLK+/-	$2xUI_{INST}$	Double UI instantaneous	4	25	ns
DSI-CLK+/-	UI_{INSTA}, UI_{INSTB}	UI instantaneous Half	2	12.5	ns

Note: $UI = UI_{INSTA} = UI_{INSTB}$

6.2 High Speed Mode – Data Clock Channel Timing

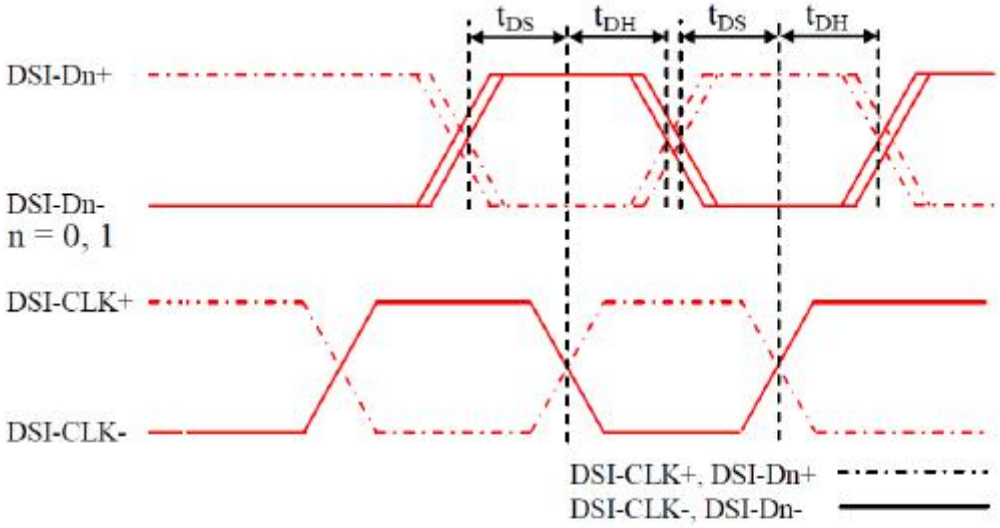


Figure 115 DSI Data to Clock Channel Timings

Table 46 DSI Data to Clock Channel Timings

Signal	Symbol	Parameter	Min	Max
DSI-Dn+/- , n=0 and 1	t_{DS}	Data to Clock Setup time	0.15xUI	-
	t_{DH}	Clock to Data Hold Time	0.15xUI	-

6.3 High Speed Mode – Rise and Fall Timings

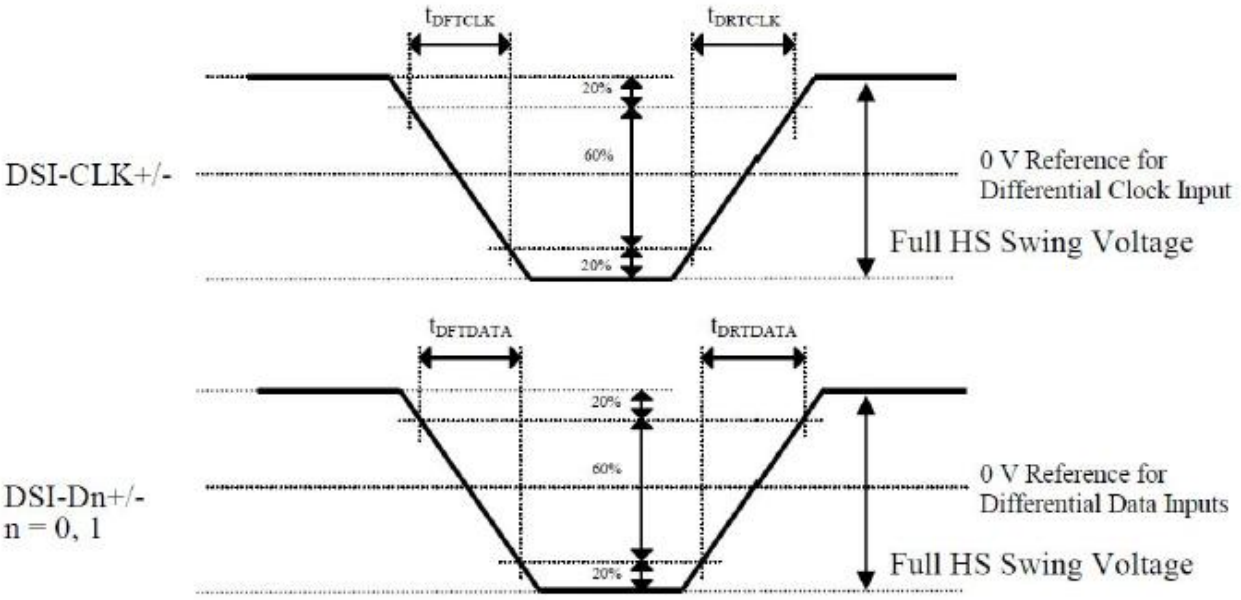


Figure 116 Rise and Fall Timings on Clock and Data Channels

Table 47 Rise and Fall Timings on Clock and Data Channels

Parameter	Symbol	Condition	Specification			
			Min	Typ	Max	Unit
Differential Rise Time for Clock	t_{DRTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Rise Time for Data	$t_{DRTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps
Differential Fall Time for Clock	t_{DFTCLK}	DSI-CLK+/-	-	-	150 (Note)	ps
Differential Fall Time for Data	$t_{DFTDATA}$	DSI-Dn+/- n=0 and 1	-	-	150 (Note)	ps

Note:The display module has to meet timing requirements, what are defined for the transmitter (MPU) on MIPI D-Phy standard

6.4 Low Speed Mode – Bus Turn Around

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the MPU to the Display Module (ILI9806E) sequence below.

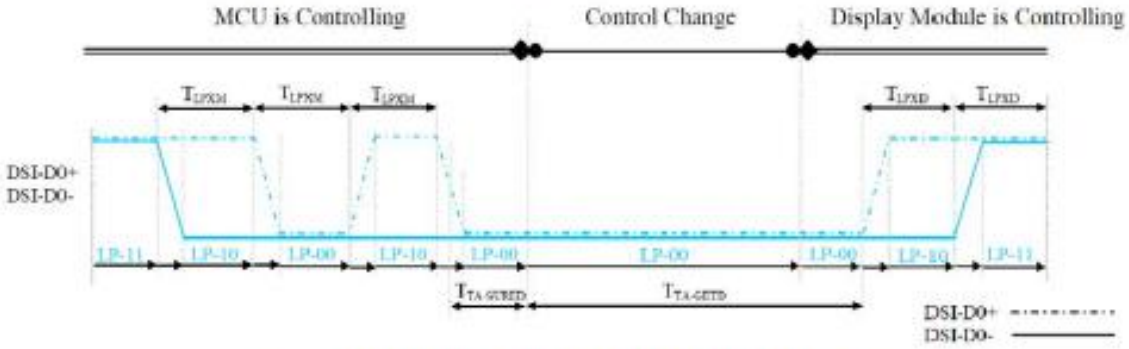


Figure 117 BTA from the MPU to the Display Module

Lower Power Mode and its State Periods are illustrated for reference purposes on the Bus Turnaround (BTA) from the Display Module (ILI9806E) to the MPU sequence below.

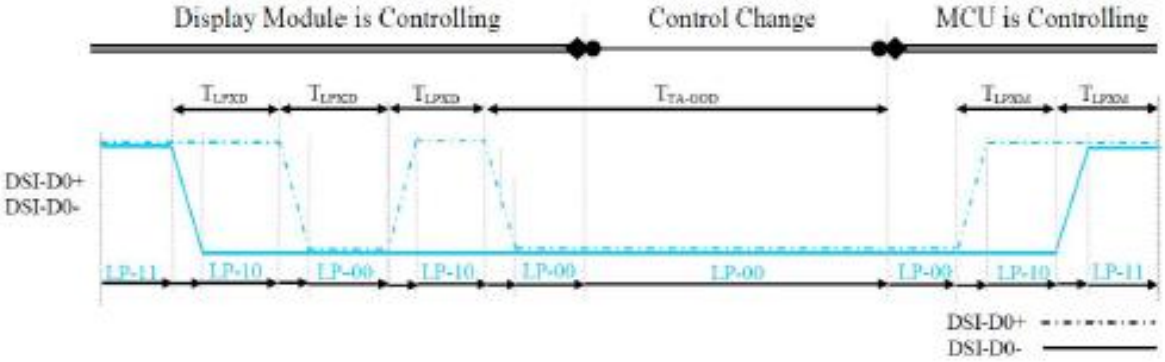


Figure 118 BTA from the Display Module to the MPU

Table 48 Low Power State Period Timings – A

Signal	Symbol	Description	Min	Max	Unit
DSI-D0+/-	T_{LPXM}	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU ➔ Display Module (ILI9806E)	50	75	ns
DSI-D0+/-	T_{LPXD}	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module (ILI9806E) ➔ MPU	50	75	ns
DSI-D0+/-	$T_{TA-SURED}$	Time-out before the Display Module (ILI9806E) starts driving	T_{LPXD}	$2\times T_{LPXD}$	ns

Table 49 Low Power State Period Timings – B

Signal	Symbol	Description	Time	Unit
DSI-D0+/-	$T_{TA-GETO}$	Time to drive LP-00 by Display Module (ILI9806E)	$5\times T_{LPXD}$	ns
DSI-D0+/-	T_{TA-GOD}	Time to drive LP-00 after turnaround request – MPU	$4\times T_{LPXD}$	ns

6.5 Data Lanes from Low Power Mode to High Speed Mode

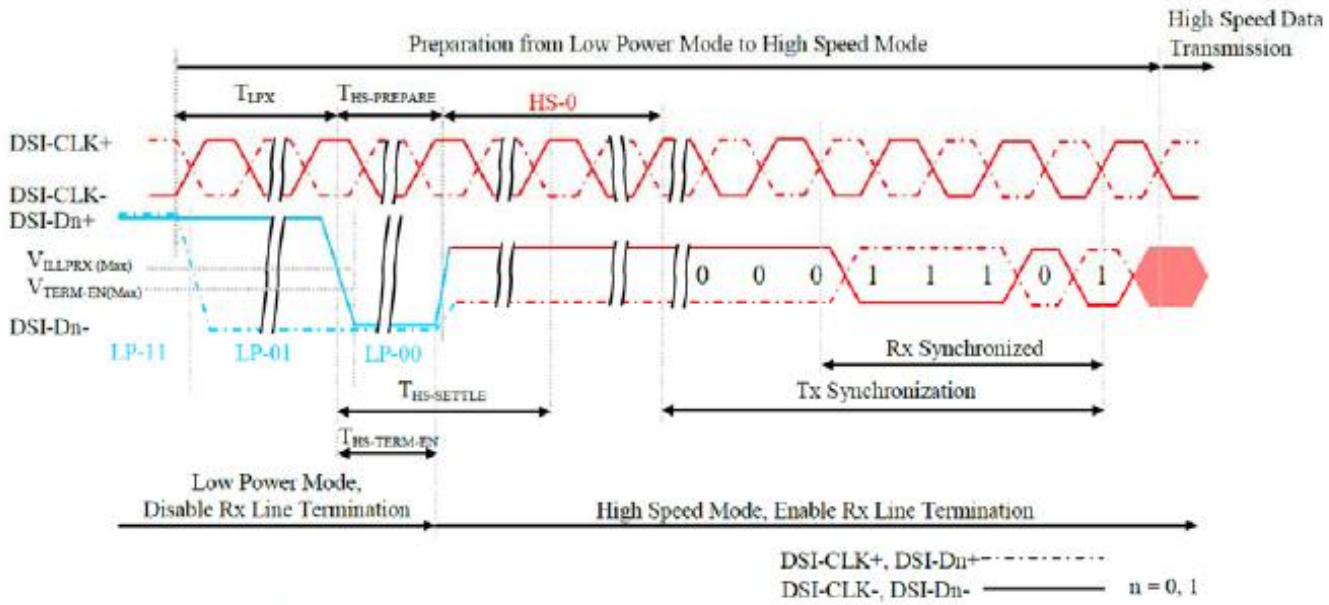


Figure 119 Data Lanes – Low Power Mode to High Speed Mode Timings

Table 50 Data Lanes – Low Power Mode to High Speed Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	T_{LPX}	Length of any Low Power State Period	50	-	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS Transmission	40+4xUI	85+6xUI	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-TERM-EN}$	Time to enable Data Lane Receiver line termination measured from when Dn crosses VILMAX	-	35+4xUI	ns

6.6 Data Lanes from Low Power Mode to High Speed Mode

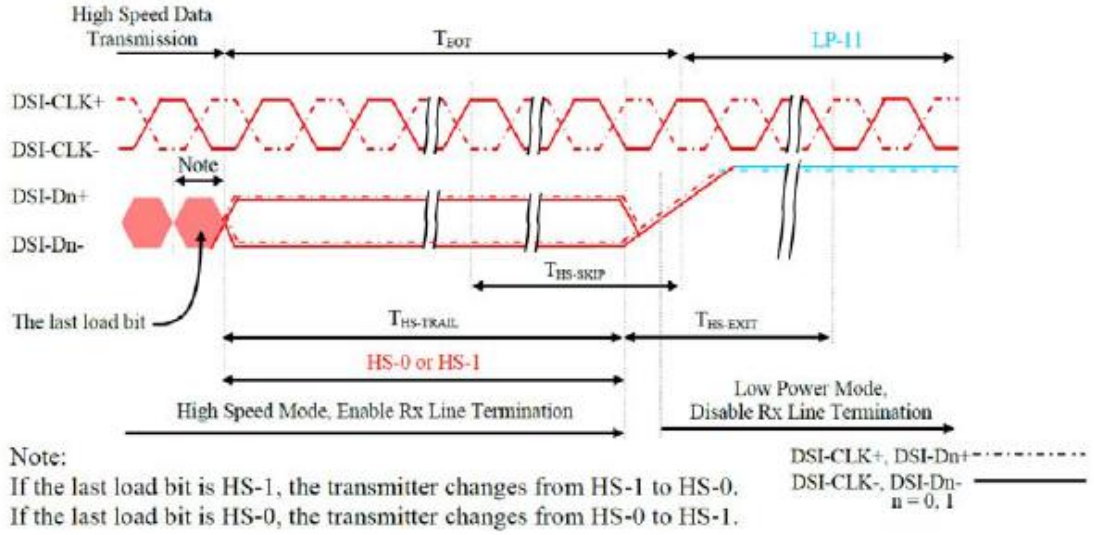


Figure 120 Data Lanes – High Speed Mode to Low Power Mode Timings

Table 51 Data Lanes – High Speed Mode to Low Power Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-Dn+/-, n=0 and 1	$T_{HS-SKIP}$	Time-Out at Display Module (ILI9806E) to ignore transition period of EoT	40	55+4xUI	ns
DSI-Dn+/-, n=0 and 1	$T_{HS-EXIT}$	Time to driver LP-11 after HS burst	100	-	ns

6.7 DSI Clock Burst – High Speed Mode to/from Low Power Mode

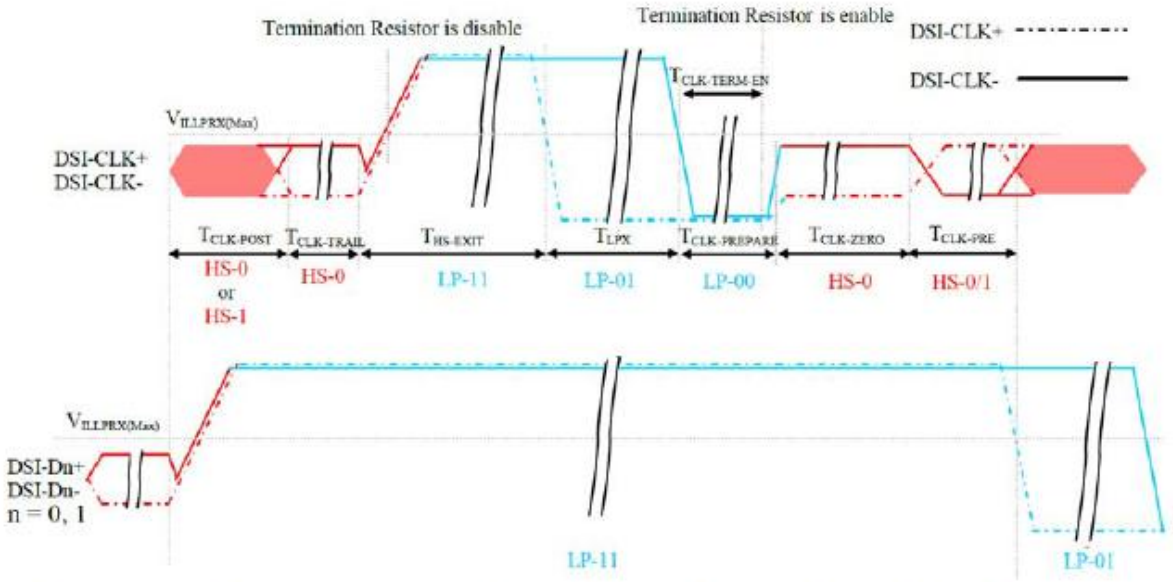


Figure 121 Clock Lanes – High Speed Mode to/from Low Power Mode Timings

Table 52 Clock Lanes – High Speed Mode to/from Low Power Mode Timings

Signal	Symbol	Description	Min	Max	Unit
DSI-CLK+/-	$T_{CLK-POST}$	Time that the MPU shall continue sending HS clock after the last associated Data Lanes has transitioned to LP mode	60+52xUI	-	ns
DSI-CLK+/-	$T_{CLK-TRAIL}$	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns
DSI-CLK+/-	$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	38	95	ns
DSI-CLK+/-	$T_{CLK-TERM-EN}$	Time-out at Clock Lane to enable HS termination	-	38	ns
DSI-CLK+/-	$T_{CLK-PREPARE}$	Minimum lead HS-0 drive period before starting Clock	300	-	ns
DSI-CLK+/-	$T_{CLK-PRE}$	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	8xUI	-	ns

6.8 Reset input timing

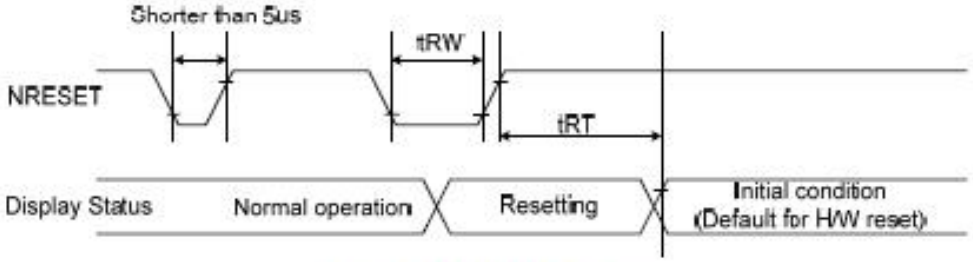


Figure 102 Reset Timing

Table 41 Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		us
	tRT	Reset cancel		5(note 1,5)	ms
				120 (note 1,6,7)	ms

Note:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 43.

Table 42 Reset Descript

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
4. Spike Rejection also applies during a valid reset pulse as shown below:

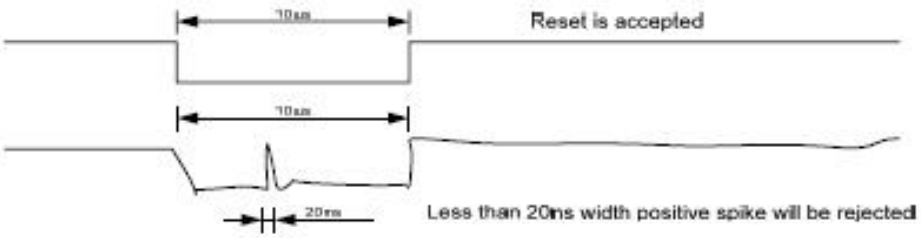


Figure 103 Positive Noise Pulse during Reset Low

5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

7. CTP Specification

7.1 Electrical Characteristics

7.1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	-0.3	3.6	V	1
I/O Digital Voltage	VDDIO	1.8	3.6	V	1
Operating temperature	T_{OP}	-20	+70	℃	-
Storage temperature	T_{ST}	-30	+80	℃	-

NOTES:

1. *If used beyond the absolute maximum ratings, FT6336G may be permanently damaged. It is strongly recommanded that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.*

7.1.2 DC Electrical Characteristics (Ta=25℃)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Digital supply voltage	VDD		2.8	3.3	3.6	V	
I/O Digital supply voltage	VDDIO		1.8	3.3	3.6	V	
Normal operation mode Current consumption	I_{opr}	VDD=2.8V Ta=25℃ MCLK= 17.5Mhz	-	4	-	mA	
Monitor mode Current consumption	I_{mon}		-	1.5	-	mA	
Sleep mode Current consumption	I_{slp}			50		uA	
Level input voltage	V_{IH}		$0.7V_{DDIO}$	-	V_{DDIO}	V	
	V_{IL}		-0.3	-	$0.3V_{DDIO}$	V	
Level output voltage	V_{OH}	I_{OH}=-0.1mA	$0.7V_{DDIO}$	-	-	V	
	V_{OL}	I_{OH}=0.1mA	-	-	$0.3V_{DDIO}$	V	

7.2 CTP AC Characteristics

Table 4-1 AC Characteristics of Oscillators

Item	Symbol	Test Condition	Min	Typ.	Max	Unit	Note
OSC clock 1	fosc1	VDDA= 2.8V; Ta=25℃	34.65	35	35.35	MHz	

Table 4-2 AC Characteristics of sensor

Item	Symbol	Test Condition	Min	Typ.	Max	Unit	Note
Sensor acceptable clock	ftx	VDDA= 2.8V; Ta=25℃	0	100	300	KHz	
Sensor output rise time	Ttxr	VDDA= 2.8V; Ta=25℃	-	100	-	nS	
Sensor output fall time	Ttxf	VDDA= 2.8V; Ta=25℃	-	80	-	nS	
Sensor input voltage	Trxi	VDDA= 2.8V; Ta=25℃	-	5	-	V	

7.2.1 I2C Interface

The I2C is always configured in the Slave mode. The data transfer format is shown in Figure4-1:

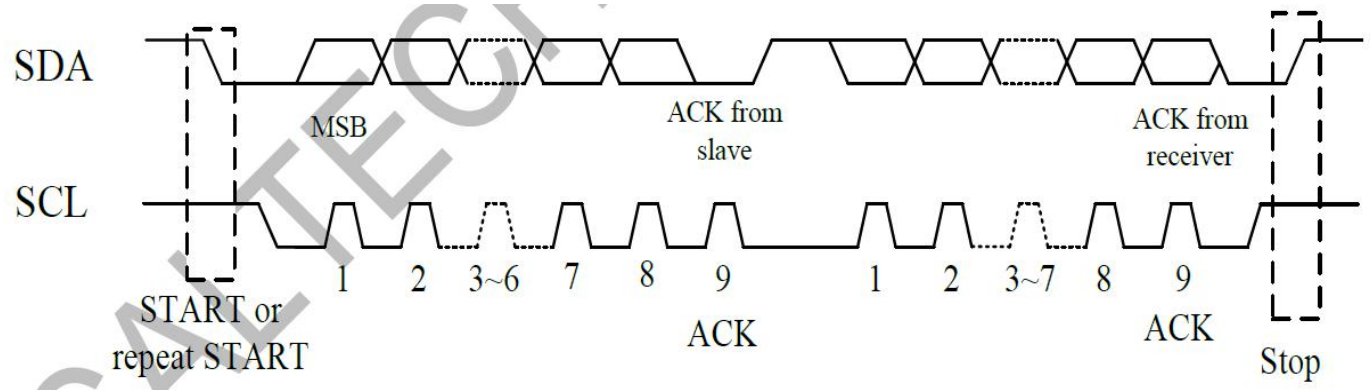


Figure 4-1 I2C Serial Data Transfer Format

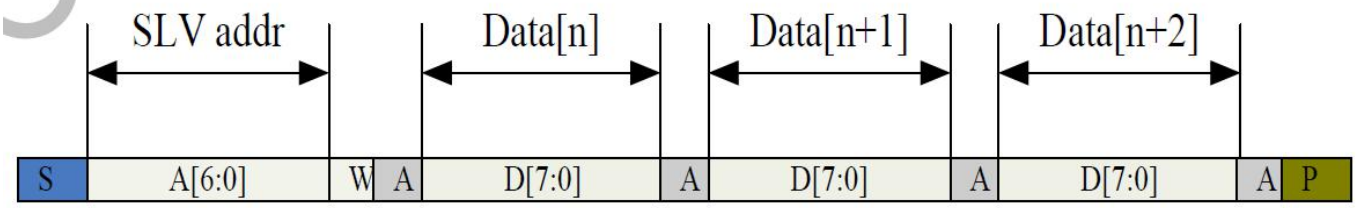


Figure 4-2 I2C master write, slave read

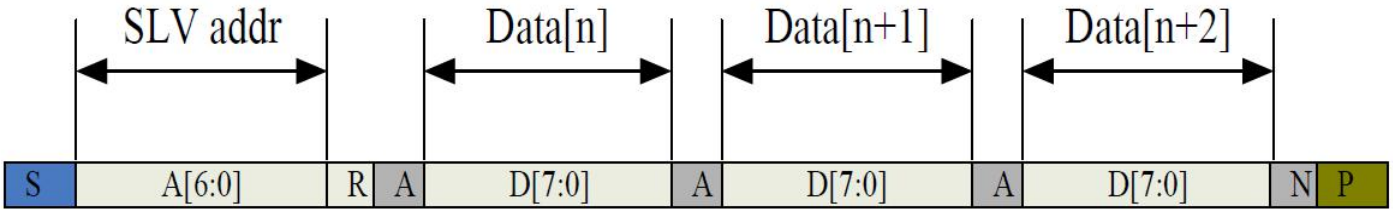


Figure 4-3 I2C master read, slave write

Table4-3 lists the meanings of the mnemonics used in the above figures.

Table 4-3 Mnemonics Description

Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address
R/W	READ/WRITE bit, '1' for read, '0'for write
A(N)	ACK(NACK)
P	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Slave address is 0x38.

I2C Interface Timing Characteristcs is shown in Table4-4.

Table 4-4 I2C Timing Characteristics

Parameter	Min	Max	Unit
SCL frequency	10	400	KHz
Bus free time between a STOP and START condition	4.7	\	us
Hold time (repeated) START condition	4.0	\	us
Data setup time	250	\	ns
Setup time for a repeated START condition	4.7	\	us
Setup Time for STOP condition	4.0	\	us

8. LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

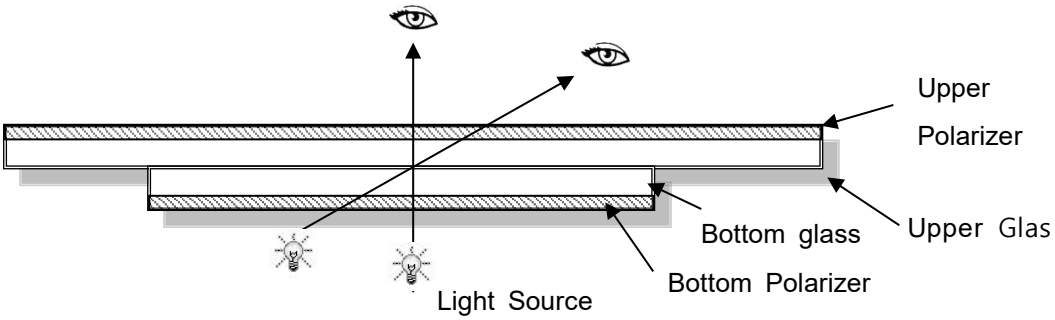
Temperature : 25±5℃

Humidity : 65%±10%RH

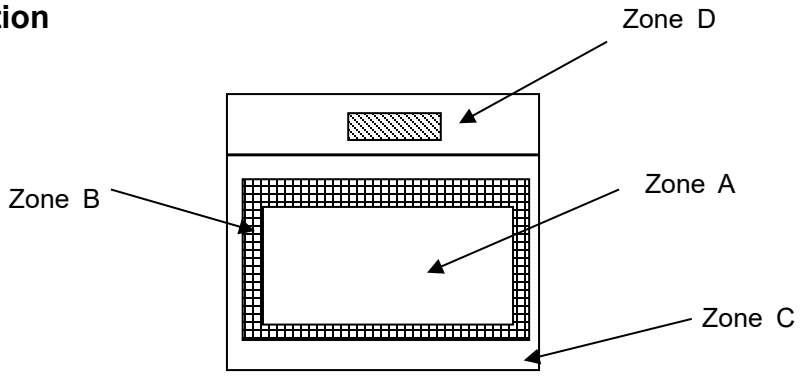
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



8.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C Cover (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note: As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class Ⅱ

AQL:

Major defect	Minor defect
0.65	1.5

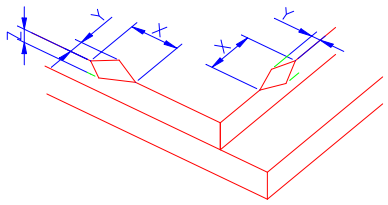
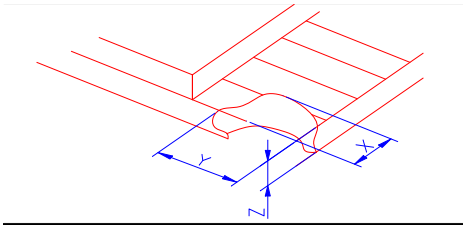
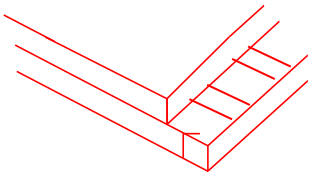
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting.	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot Line defect	Light dot, Dim spot,Polarizer Bubble ; Polarizer accidented spot.	
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/CTP	Black/White spot/line, scratch, crack, etc.	

Note1: a) Light dot：Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

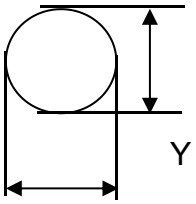
b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

8.1.4 Criteria (Visual)

<table>
<tr><th>Number</th><th>Items</th><th>Criteria(mm)</th></tr>
<tr><td rowspan="3">1.0 LCD Crack/Broken
NOTE:
X: Length
Y: Width
Z: Height
L: Length of ITO,
T: Height of LCD</td><td>(1) The edge of LCD broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table></td></tr>
<tr><td>(2)LCD corner broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table></td></tr>
<tr><td>(3) LCD crack</td><td> 
Crack
Not allowed</td></tr>
</table>

2.0

Spot defect



Φ=(X+Y)/2

① light dot (black/white spot , pinhole, stain，etc.)

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.15	Ignore	Ignore	
0.15<Φ≤0.25	3(distance≧10mm)		
0.25<Φ≤0.4	2(distance≧10mm)		
Φ>0.4	0		

② Dim spot (light leakage、dent、dark spot，etc)

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.15	Ignore	Ignore	
0.15<Φ≤0.25	3(distance≧10mm)		
0.25<Φ≤0.4	2(distance≧10mm)		
Φ>0.4	0		

③ Polarizer accidented spot

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.2<Φ≤0.5	2(distance≧10mm)		
Φ>0.5	0		

④Polarizer Bubble

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.2<Φ≤0.4	3(distance≧10mm)		
Φ>0.4	0		

3.0 LCD Pixel defect

Pixel bad points

Item	Zone A	Acceptable Qt
Bright dot	Random	N≤2
	2 dots adjacent	N≤0
	3 dots adjacent	N≤0
Dark dot	Random	N≤2
	2 dots adjacent	N≤0
	3 dots adjacent	N≤0
Distance	1. Minimum Distance Between Bright dots. 2. Minimum Distance Between dark dots 3. Minimum Distance Between dark and bright dot.	5mm
Total bright and dark dot		N≤4

Note:

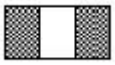
A) Bright dot：Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

B) Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

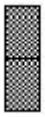
C) 2 dot adjacent = 1 pair = 2 dots

Picture:

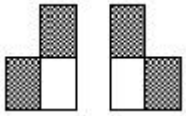
2 dot adjacent



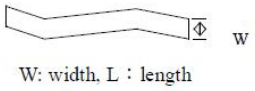
2 dot adjacent



2 dot adjacent (vertical)



2 dot adjacent (slant)

<table>
<tr>
<td>4.0</td>
<td>Line defect (LCD /Polarizer backlight black/white line, scratch, stain)
 

W: width, L：length
N：Count</td>
<td>
<table>
<tr><td rowspan="2">Width(mm)</td><td rowspan="2">Length(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.05</td><td>Ignore</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.05<W≤0.06</td><td>L≤4.0</td><td colspan="2">N≤3</td></tr>
<tr><td>0.06<W≤0.08</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>W>0.08</td><td colspan="4">Define as spot defect</td></tr>
</table>
</td>
</tr>
<tr>
<td>5.0</td>
<td>Electronic Components SMT.</td>
<td>Not allow missing parts，solderless connection，cold solder joint，mismatch，The positive and negative polarity opposite</td>
</tr>
<tr>
<td>6.0</td>
<td>Display color& Brightness.</td>
<td>1. Color：Measuring the color coordinates, The measurement standard according to the datasheet or samples.
2. Brightness：Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.</td>
</tr>
<tr>
<td>7.0</td>
<td>LCD Mura/Waving/ Hot spot</td>
<td>Not visible through 5% ND filter in 50% gray or judge by limit sample if necessary.</td>
</tr>
<tr>
<td>8.0</td>
<td>CTP Related</td>
<td>CTP Cover sensor accidented black/white spot</td>
<td>
<table>
<tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.1<Φ≤0.2</td><td colspan="2"></td></tr>
<tr><td>0.20<Φ≤0.25</td><td colspan="2"></td></tr>
<tr><td>Φ > 0.25</td><td colspan="2">0</td></tr>
</table>
</td>
</tr>
</table>

CTP Cover scratch

Width(mm)	Ignore (mm)	Acceptable Qty		
		A	B	C
Φ≤0.05	Ignore	Ignore		
0.05<W≤0.06	L≤4.0	N≤3		
0.06<W≤0.08	L≤3.0	N≤2		
0.08<W	Define as spot defect			

CTP Cover Pinhole/ Lack of ink

Zone / Size (mm)	Acceptable Qty
	C
Φ≤0.1	Ignore
0.1<Φ≤0.25	3(distance≧10mm)
0.25<Φ≤0.3	2(distance≧10mm)
Φ>0.3	0

CTP Bonding bubble/ accidented spot

Size Φ(mm)	Acceptable Qty	
	A	B
Φ≤0.1	Ignore	
0.1<Φ≤0.2	2(distance≧10mm)	
0.2<Φ≤0.25	2(distance≧10mm)	
Φ>0.25	0	

Assembly deflection

beyond the edge of backlight ≤0.2mm

CTP cover broken

X : length

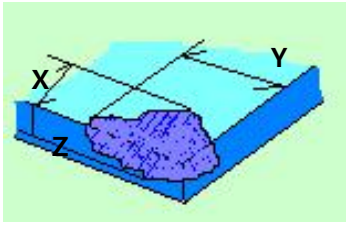
Y : width

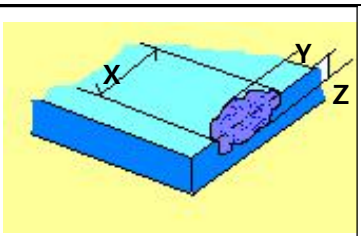
Z : height

X	Y	Z
X≤0.5mm	Y≤0.5mm	Z<cover thickness

*

Circuitry broken is not allowed.



		CTP cover broken X : length Y : width Z : height	X: X≤0.3mm; Y: Y≤0.3mm; Z: Z<cover thickness * Circuitry broken is not allowed.	

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	CTP no function	Not allowed

9. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70℃,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-20℃, 96HR	
High Temperature Storage	80℃, 96HR	
Low Temperature Storage	-30℃, 96HR	
High Temperature & High Humidity Operating	+60℃, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-10℃,30 min ↔ +60℃,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15℃~35℃, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80㎝(MEDIUM BOX)	

Remark:

1.The test samples should be applied to only one test item.

2.Sample size for each test item is 5~10pcs.

3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

6. The color fading mura of polarizing filter should not care.

10. Cautions and Handling Precautions

10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
(4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
(8) Protect the module from static; it may cause damage to the CMOS ICs.
(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
(10) Do not disassemble the module.
(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
(12) Pins of I/F connector shall not be touched directly with bare hands.
(13) Do not connect, disconnect the module in the “Power ON” condition.
(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 ℃ and relative humidity of less than 70%
(2) Do not store the TFT-LCD module in direct sunlight.
(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

11. Packing

----TBD----------